

May 2001

FQP20N06

60V N-Channel MOSFET

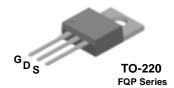
General Description

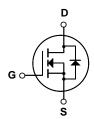
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/ DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- 20A, 60V, $R_{DS(on)}$ = 0.06 Ω @V_{GS} = 10 V Low gate charge (typical 11.5 nC)
- Low Crss (typical 25 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP20N06	Units
V _{DSS}	Drain-Source Voltage		60	V
I _D	Drain Current - Continuous (T _C = 25°C	C)	20	А
	- Continuous (T _C = 100°C)		14.1	А
I _{DM}	Drain Current - Pulsed	(Note 1)	80	А
V _{GSS}	Gate-Source Voltage		± 25	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	155	mJ
I _{AR}	Avalanche Current	(Note 1)	20	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.3	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
P_D	Power Dissipation (T _C = 25°C)		53	W
	- Derate above 25°C		0.35	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.85	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25	C	0.07		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60 V, V _{GS} = 0 V			1	μА
		V _{DS} = 48 V, T _C = 150°C			10	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		0.048	0.06	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 25 V, I _D = 10 A (Note	4)	12		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		170 25	590 220 35	pF pF
	,			25	- 33	Pi
	Ing Characteristics Turn-On Delay Time			-	20	no
t _{d(on)}	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 10 \text{ A},$		5 45	20 100	ns
t _r	Turn-Off Delay Time	$R_G = 25 \Omega$		20	50	ns ns
t _{d(off)}	Turn-Off Fall Time	(Note 4,		25	60	ns
Q _g	Total Gate Charge	•		11.5	15	nC
Q _{gs}	Gate-Source Charge	$V_{DS} = 48 \text{ V}, I_{D} = 20 \text{ A},$ $V_{GS} = 10 \text{ V}$		3		nC
Q _{gd}	Gate-Drain Charge	VGS = 10 V (Note 4,	5)	4.5		nC
gu	- carre - rame crisings	, ,				
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				20	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current			80	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 20 \text{ A}$			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 20 \text{ A},$		43		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note	4)	50		nC

Notes:1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 450μH, I_{AS} = 20A, V_{DD} = 25V, R_G = 25 Ω, Starting T_J = 25°C 3. lg_D < 20A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

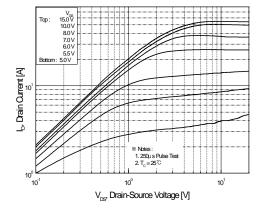


Figure 1. On-Region Characteristics

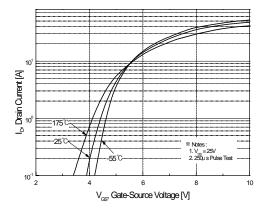


Figure 2. Transfer Characteristics

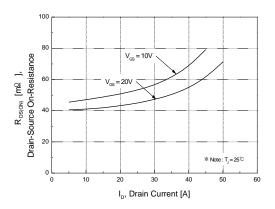


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

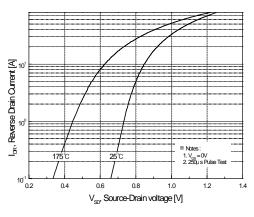


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

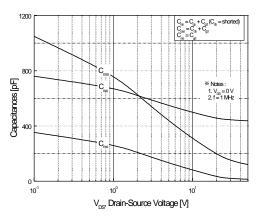


Figure 5. Capacitance Characteristics

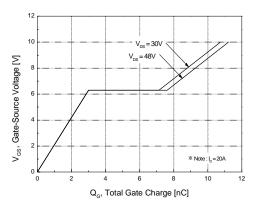


Figure 6. Gate Charge Characteristics

Rev. A1. May 2001

©2001 Fairchild Semiconductor Corporation



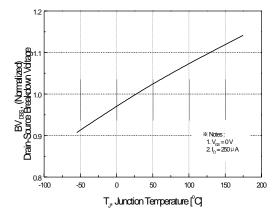


Figure 7. Breakdown Voltage Variation vs. Temperature

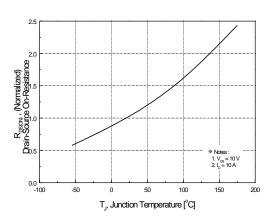


Figure 8. On-Resistance Variation vs. Temperature

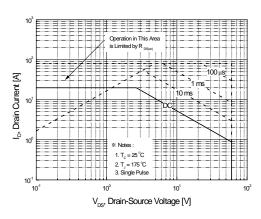


Figure 9. Maximum Safe Operating Area

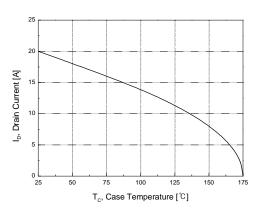


Figure 10. Maximum Drain Current v.s Case Temperature

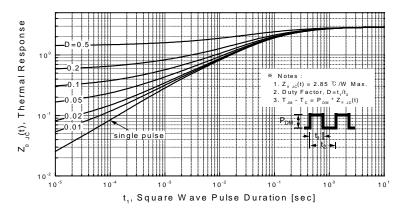
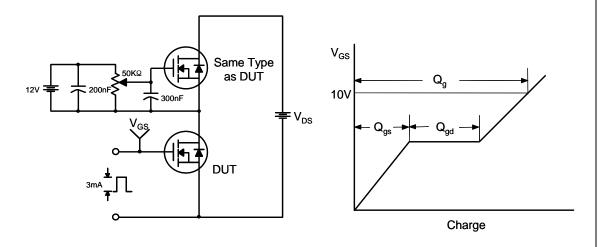


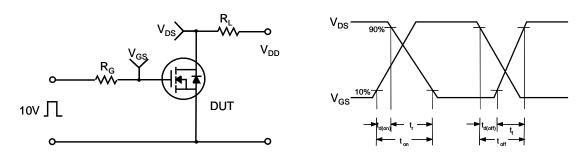
Figure 11. Transient Thermal Response Curve

©2001 Fairchild Semiconductor Corporation Rev. A1. May 2001

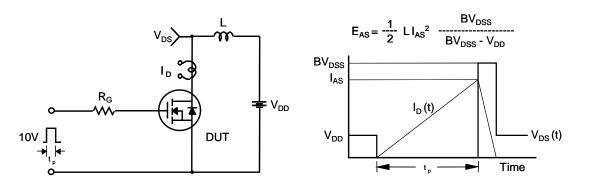
Gate Charge Test Circuit & Waveform



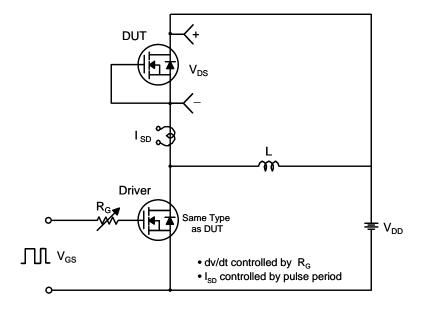
Resistive Switching Test Circuit & Waveforms

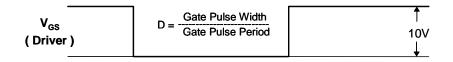


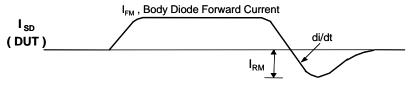
Unclamped Inductive Switching Test Circuit & Waveforms



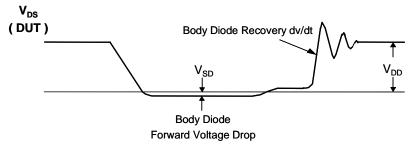
Peak Diode Recovery dv/dt Test Circuit & Waveforms

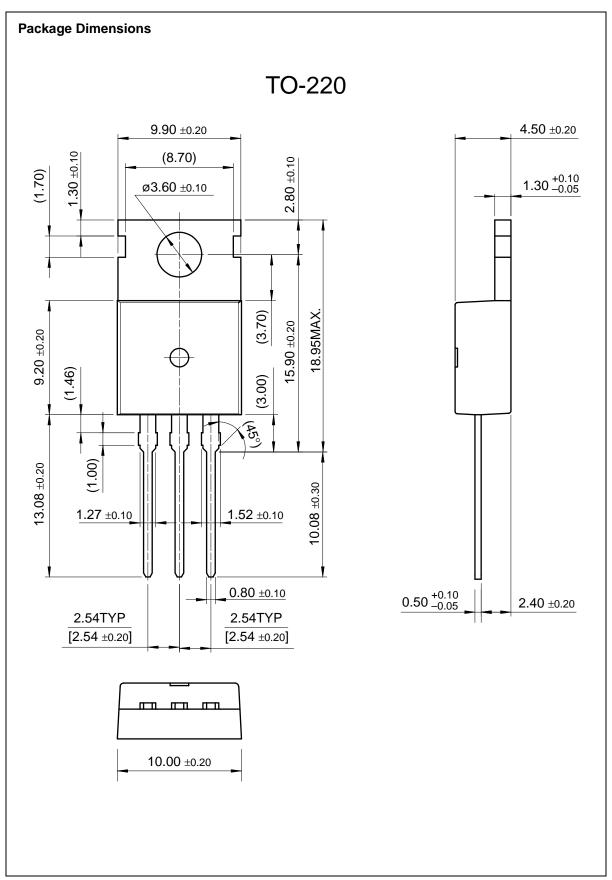






Body Diode Reverse Current





TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

$ACEx^{TM}$	FAST [®]	OPTOPLANAR™	SuperSOT™-3
Bottomless™	FASTr™	PACMAN™	SuperSOT™-6
CoolFET™	FRFET™	POP™	SuperSOT™-8
CROSSVOLT™	GlobalOptoisolator™	PowerTrench [®]	SyncFET™
DenseTrench™	GTO™	QFET™	TinyLogic™
DOME™	HiSeC™	QS™	UHC™
EcoSPARK™	ISOPLANAR™	QT Optoelectronics™	UltraFET [®]
E ² CMOS™	LittleFET™	Quiet Series™	VCX™
EnSigna™	MicroFET™	SLIENT SWITCHER®	
FACT™	MICROWIRE™	SMART START™	
FACT Quiet Series™	OPTOLOGIC™	Stealth™	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

©2001 Fairchild Semiconductor Corporation Rev. H2